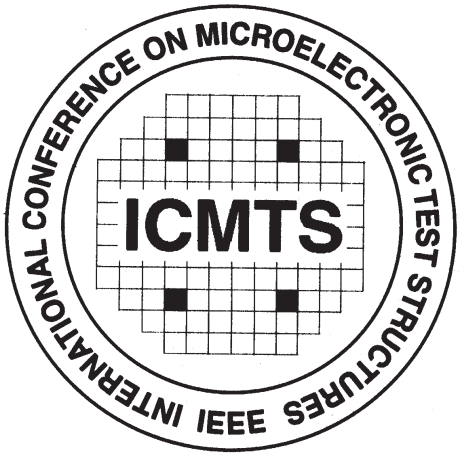
2016 International Conference on Microelectronic Test Structures



29th IEEE ICMTS Conference Proceedings

March 28-31

Mielparque Yokohama, Japan

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CHAIRMAN'S LETTER

Dear Colleagues,

The 29th IEEE International Conference on Microelectronic Test Structures (ICMTS 2016) will be held in Yokohama, Japan, on March 28-31. Test structures are indispensable for the development, design and production of any microelectronic circuits, devices and processes. Since 1988, ICMTS has provided a forum for designers and users of test structures in all areas of microelectronics, to discuss recent developments and future directions. This year, the conference consists of about 40 oral presentations in ten sessions. As usual, it will be preceded by a one-day tutorial short course. There will also be an equipment exhibition related to test structure measurements. The conference is technically co-sponsored by the IEEE Electron Devices Society.

This is the first time the conference is held in the port city Yokohama. The conference venue, Mielparque Yokohama, is comfortably located just in front of a seaside park within an old town area. It is also very close (only two minutes walk) to a subway station, from which convenient access to the airports, as well as nearby locations including central Tokyo is provided. Since Yokohama is a major tourist destination, you can find abundant shops, restaurants and other tourist attractions around.

I look forward to your participation in ICMTS 2016!

Sincerely,

Kiyoshi Takeuchi
General Chairman

SESSION 1: MEMS and Sensors

2016 March 29, 9:00 – 10: 20

Co-Chairs: Stewart Smith, *The University of Edinburgh, UK*

SESSION 2: Thermal Issues

2016 Mar 29, 11:00 – 12:20

Co-Chairs: Anthony J. Walton, *University of Edinburgh, UK*
Hi-Deok Lee, *Chungnam National University, Korea*

SESSION 3: Arrayed Test Structures

2016 Mar 29, 14:10 – 15:40

Co-Chairs: Tatsuya Ohguro, *Toshiba, Japan*
Christopher Hess, *PDF Solutions, USA*

SESSION 4: Parameter Extraction

2016 Mar 29 16:10 – 17:10

Co-Chairs: Kjell Jeppson, *Chalmers University, Sweden*

SESSION 5: RF and Power Devices

2016 Mar 30 9:20 – 10:20

Co-Chairs: Colin McAndrew, *NXP Semiconductors, USA*

SESSION 6: Capacitances

2016 Mar 30 10:50 – 11:50

Co-Chairs: Hans P. Tuinhout, *NXP Semiconductor, The Netherlands*
Chadwin Young, *University of Texas at Dallas, USA*

SESSION 7: Memories

2016 Mar 30 13:40 – 14:40

Co-Chairs: Yuzo Fukuzaki, *Sony Corporation, Japan*
Carlo Cagli, *CEA/LETI, France*

SESSION 8: Non-Volatile Memories

2016 Mar 30 15:30 – 17:00

Co-Chairs: Jurriaan Schmitz*, University of Twente, The Netherlands*
Satoshi Habu, *Keysight Technologies, Japan*

SESSION 9: Process and Device Characterization

2016 Mar 31 9:00 – 10:20

Co-Chairs: Larg Weiland, *PDF Solutions, USA*
Bing-Yue Tsui, *National Chiao Tung University, Taiwan*

SESSION 10: Materials Characterization

2016 Mar 31 10:50 – 12:10

Co-Chairs: Bill Verzi, *Agilent Technologies, USA*

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† Loren Linholm passed away on 18 January 2016.

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